# Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment\*

### DIGI-KEY PART # ATS1058-ND

ATS PART # ATS-51330D-C2-R0

#### Features & Benefits

maxiFLOW<sup>™</sup> design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

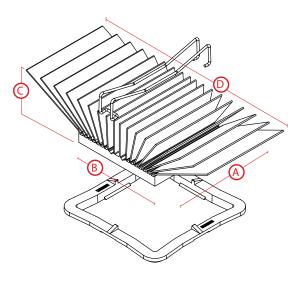
maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards

Comes preassembled with high performance, phase changing, thermal interface material

**Thermal Performance Table** 

Designed for low profile components from 1.5 to 2.99mm





#### **AIR VELOCITY** THERMAL RESISTANCE °C/W (DUCTED) FT/MIN M/S °C/W (UNDUCTED) 5.9 200 1.0 3.8 4.5 300 1.5 3.9 400 2.0 3.5 500 2.5 3.2 600 3.0 700 3.5 2.9 800 4.0 2.7

## **Product Details**<sup>†</sup>

DIMENSION A	DIMENSION B	DIMENSION C <sup>§</sup>	DIMENSION D	TIM <sup>‡</sup>	FINISH
33	33	9.5	45.5	C1100F	BLACK- ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com** 

\* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters

Dimensions A & B refer to component size
Dimension C = the height of the heat sink shown above

and does not include the height of the attachment method



